

Pin Descriptions

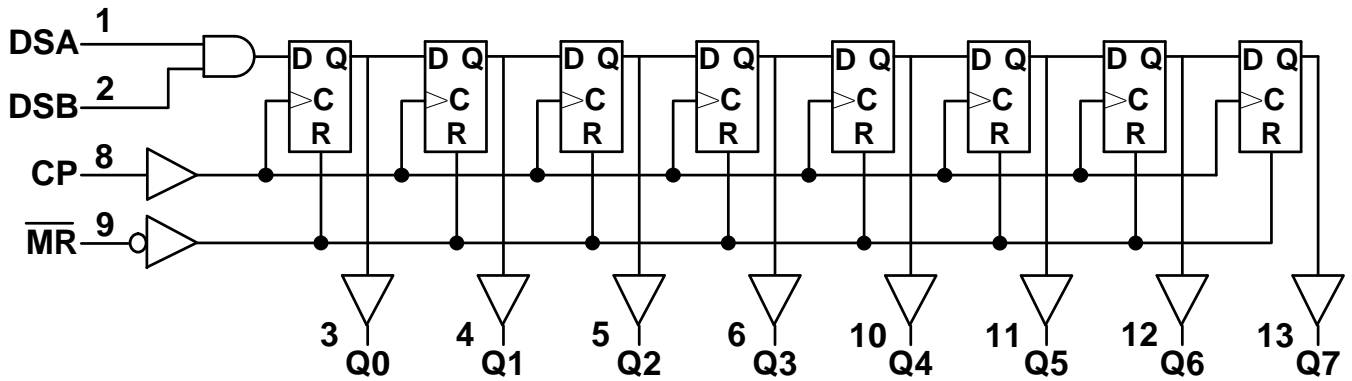
Pin Number	Pin Name	Function
1	DSA	Serial Data Input
2	DSB	Serial Data Input
3	Q0	Data Output
4	Q1	Data Output
5	Q2	Data Output
6	Q3	Data Output
7	GND	Ground
8	CP	Clock Pulse –Positive Edge Triggered
9	$\overline{\text{MR}}$	Master Reset - Asynchronous
10	Q4	Data Output
11	Q5	Data Output
12	Q6	Data Output
13	Q7	Data Output
14	Vcc	Supply Voltage

Function Table (Note 4)

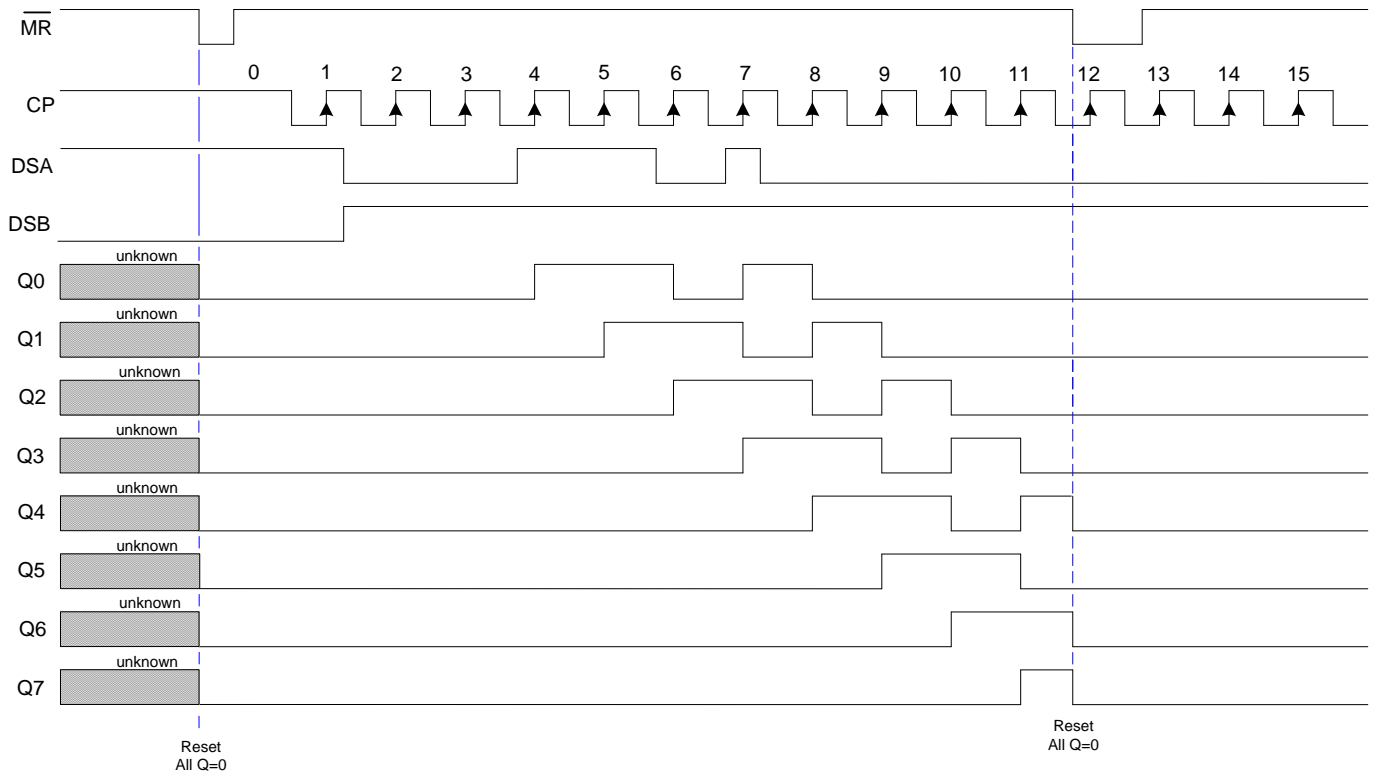
Mode	Input				Output	
	$\overline{\text{MR}}$	CP	DSA	DSB	Q0	Q1-Q7
Reset	L	X	X	X	L	L
Shift	H	↑	L	X	L	Q _n ←Q _{n-1} (n= 1 to7)
	H	↑	X	L	L	Q _n ←Q _{n-1} (n= 1 to7)
	H	↑	H	H	H	Q _n ←Q _{n-1} (n= 1 to7)

Note: 4. Signals asserted on DSA and DSB must be in place longer than Tsu (set up time) before CP occurs and remain in place Thold (hold time) after CP.

Logic Diagram



Timing Diagram



- Notes:
5. All Q values are reset to LOW when \overline{MR} goes low. \overline{MR} is asynchronous and overrides all other signals.
 6. Serial data supplied at DSA and DSB is ANDED and transferred to Q0 on positive edge of CP.

Absolute Maximum Ratings (Note 7) ($T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to +7.0	V
V_I	Input Voltage Range (Note 8)	-0.5 to +7.0	V
I_{IK}	Input Clamp Current $V_I < -0.5\text{V}$	-20	mA
I_{OK}	Output Clamp Current $V_O < -0.5\text{V}$ or $V_O > V_{CC} + 0.5\text{V}$	± 20	mA
I_O	Continuous Output Current $-0.5\text{V} < V_O < V_{CC} + 0.5\text{V}$	± 25	mA
I_{CC}	Continuous Current Through V_{CC}	75	mA
I_{GND}	Continuous Current Through GND	-75	mA
T_J	Operating Junction Temperature	-40 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature	-65 to +150	$^\circ\text{C}$
P_{TOT}	Total Power Dissipation	500	mW

Notes: 7. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
 8. Input Voltage cannot exceed V_{CC} to the extent the Maximum clamp current is exceeded.

Recommended Operating Conditions (Note 9) ($T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply Voltage	-	2.0	5.5	V
V_I	Input Voltage	-	0	5.5	V
V_O	Output Voltage	-	0	V_{CC}	V
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	$V_{CC} = 3.0\text{V}$ to 3.6V	-	100	ns/V
		$V_{CC} = 4.5\text{V}$ to 5.5V	-	20	
T_A	Operating Free-Air Temperature	-	-40	+125	$^\circ\text{C}$

Note: 9. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics ($T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V _{CC}	T _A = +25°C			T _A = -40°C to +85°C		T _A = -40°C to +125°C		Unit	
				Min.	Typ.	Max.	Min.	Max.	Min.	Max.		
V _{IH}	High-Level Input Voltage	-	2.0V	1.5	-	-	1.5	-	1.5	-	V	
			3.0V	2.1	-	-	2.1	-	2.1	-		
			5.5V	3.85	-	-	3.85	-	3.85	-		
V _{IL}	Low-Level Input Voltage	-	2.0V	-	-	0.5	-	0.5	-	0.5	V	
			3.0V	-	-	0.9	-	0.9	-	0.9		
			5.5V	-	-	1.65	-	1.65	-	1.65		
V _{OH}	High-Level Output Voltage	-	I _{OH} = -50μA	2.0V	1.9	2.0	-	1.9	-	1.9	-	V
			I _{OH} = -50μA	3.0V	2.9	3.0	-	2.9	-	2.9	-	
			I _{OH} = -50μA	4.5V	4.4	4.5	-	4.4	-	4.4	-	
			I _{OH} = -4.0mA	3.0V	2.58	-	-	2.48	-	2.40	-	
			I _{OH} = -8mA	4.5V	3.94	-	-	3.80	-	3.70	-	
V _{OL}	Low-Level Output Voltage	-	I _{OL} = 50μA	2.0V	-	0	0.1	-	0.1	-	0.1	V
			I _{OL} = 50μA	3.0V	-	0	0.1	-	0.1	-	0.1	
			I _{OL} = 50μA	4.5V	-	0	0.1	-	0.1	-	0.1	
			I _{OL} = 4mA	3.0V	-	0.15	0.36	-	0.44	-	0.55	
			I _{OL} = 8mA	4.5V	-	0.15	0.36	-	0.44	-	0.55	
I _I	Input Current	V _I = GND or 5.5V	0V or 5.5V	-	-	±0.1	-	±1	-	±2	μA	
I _{CC}	Supply Current	V _I = GND or V _{CC} , I _O = 0A	5.5V	-	-	4.0	-	40	-	80	μA	

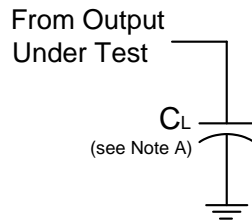
Switching Characteristics

Symbol / Parameter	Pins	Test Conditions Figure 1	V _{CC}	T _A = +25°C			-40°C to +85°C		-40°C to +125°C		Unit
				Min	Typ.	Max	Min	Max	Min	Max	
f _{MAX} Maximum Frequency	CP	C _L = 15pF	3.0V to	80	125	-	65	-	50	-	MHz
		C _L = 50pF	3.6V	50	75	-	45	-	35	-	
		C _L = 15pF	4.5V to	125	175	-	105	-	85	-	
		C _L = 50pF	5.0V	85	115	-	75	-	65	-	
t _w Pulse Width	CP HIGH or LOW	-	3.0V to 3.6V	5.0	-	-	5.0	-	5.0	-	ns
		-	4.5V to 5.0V	5.0	-	-	5.0	-	5.0	-	
	MR LOW	-	3.0V to 3.6V	5.0	-	-	5.0	-	5.0	-	ns
		-	4.5V to 5.0V	5.0	-	-	5.0	-	5.0	-	
t _{SU} Set-up Time	DSA or DSB to CP	-	3.0V to 3.6V	5.0	-	-	6.0	-	6.0	-	ns
		-	4.5V to 5.0V	4.5	-	-	4.5	-	4.5	-	
t _H Hold Time	DSA or	-	3.0V to 3.6V	1.5	-	-	1.5	-	1.5	-	ns
		-	4.5V to 5.0V	2.0	-	-	2.0	-	2.0	-	
t _{rec} Recovery Time	MR to CP	-	3.0V to 3.6V	2.5	-	-	2.5	-	2.5	-	ns
		-	4.5V to 5.0V	2.5	-	-	2.5	-	2.5	-	
t _{PD} Propagation Delay	CP to Qn	C _L = 15pF	3.0V to	-	6.5	12.8	1.0	15.0	1.0	16.0	ns
		C _L = 50pF	3.6V	-	9.3	16.3	1.0	18.5	1.0	20.5	
		C _L = 15pF	4.5V to	-	4.5	9.0	1.0	10.5	1.0	11.5	
		C _L = 50pF	5.0V	-	6.4	11.0	1.0	12.5	1.0	14.0	
	MR to Qn	C _L = 15pF	3.0V to	-	5.3	12.8	1.0	15.0	1.0	16.0	ns
		C _L = 50pF	3.6V	-	7.6	16.3	1.0	18.5	1.0	20.5	
		C _L = 15pF	4.5V to	-	4.0	8.6	1.0	10.0	1.0	11.0	
		C _L = 50pF	5.0V	-	5.8	10.6	1.0	12.0	1.0	13.5	

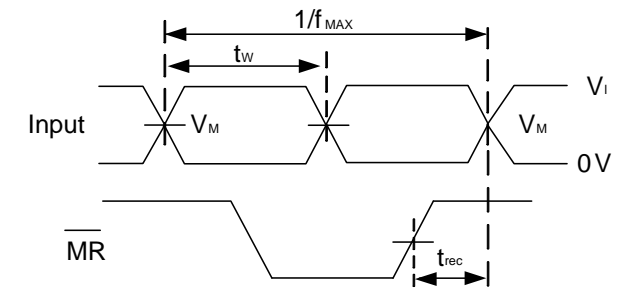
Operating Characteristics (T_A = +25°C, unless otherwise specified.)

Parameter		Test Conditions	V _{CC} = 5.5V		Unit
			Typ	Maximum	
C _{pd}	Power Dissipation Capacitance per Gate	f = 1 MHz	51	-	pF
C _I	Input Capacitance	V _I = V _{CC} or GND	3	10	pF

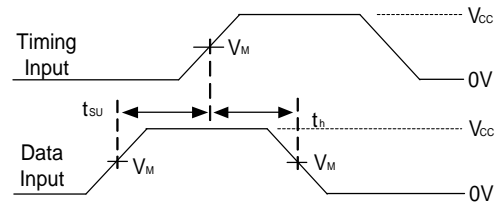
Parameter Measurement Information



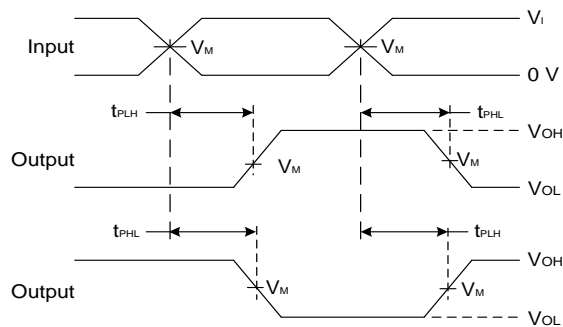
V_{CC}	Inputs		V_M	C_L
	V_I	t_r/t_f		
3.0V-3.6V	V_{CC}	$\leq 3ns$	$V_{CC}/2$	15pF, 50pF
4.5V-5.5V	V_{CC}	$\leq 3ns$	$V_{CC}/2$	15pF, 50pF



**Voltage Waveform
Pulse Duration and Recovery Time**



**Voltage Waveform
Set-up and Hold Times**

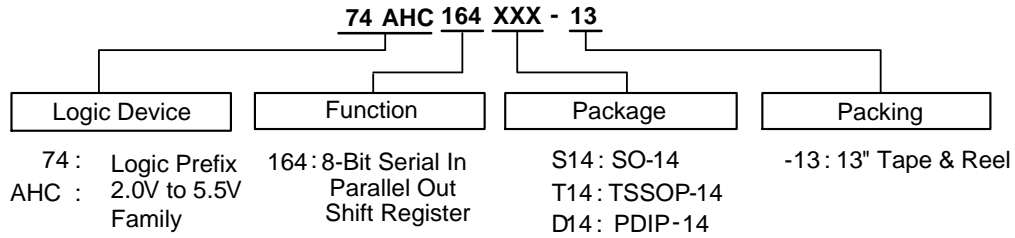


**Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs**

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD} .

Figure 1 Load Circuit and Voltage Waveforms

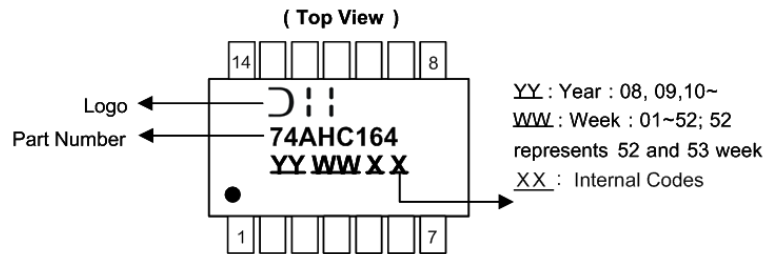
Ordering Information



Device	Package Code	Packaging	Packing	
			Quantity	Part Number Suffix
74AHC164S14-13	S14	SO-14	2,500/Tape & Reel	-13
74AHC164T14-13	T14	TSSOP-14	2,500/Tape & Reel	-13
74AHC164D14	D14	PDIP-14	Tube	

Marking Information

(1) SO-14, TSSOP-14, PDIP-14

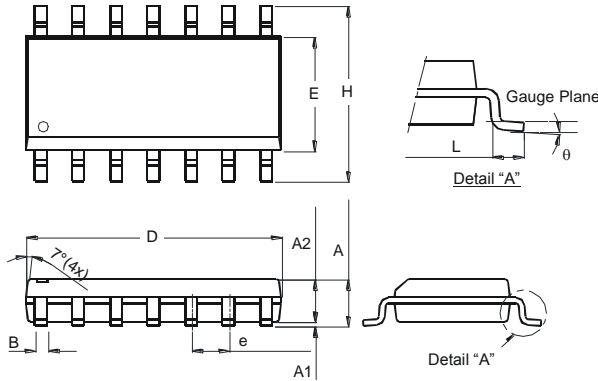


Part Number	Package
74AHC164S14-13	SO-14
74AHC164T14-13	TSSOP-14
74AHC164D14	PDIP-14

Package Outline Dimensions (All dimensions in mm.)

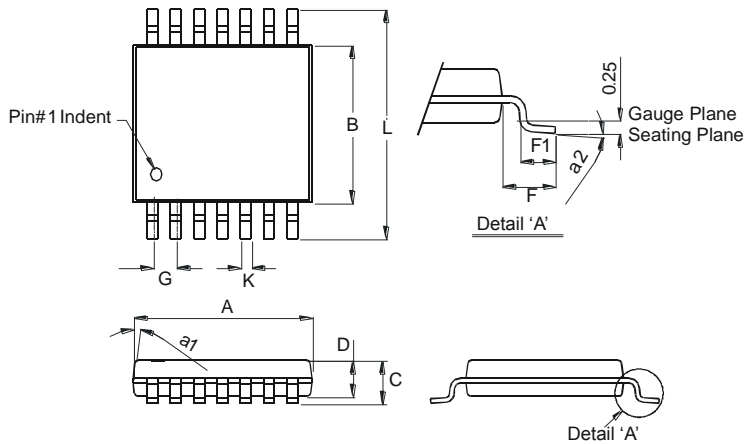
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.

Package Type: SO-14



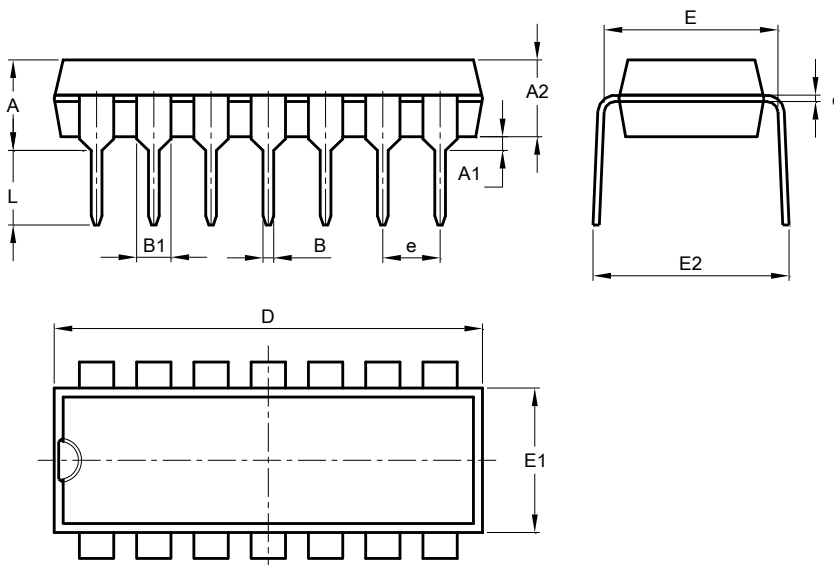
SO-14		
Dim	Min	Max
A	1.47	1.73
A1	0.10	0.25
A2	1.45 Typ	
B	0.33	0.51
D	8.53	8.74
E	3.80	3.99
e	1.27 Typ	
H	5.80	6.20
L	0.38	1.27
θ	0°	8°
All Dimensions in mm		

Package Type: TSSOP-14



TSSOP-14		
Dim	Min	Max
a1	7° (4X)	
a2	0°	8°
A	4.9	5.10
B	4.30	4.50
C	—	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
L	6.40 Typ	
All Dimensions in mm		

Package Type: PDIP-14

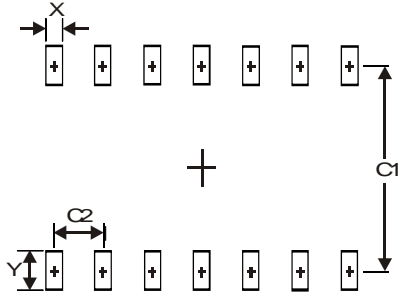


PDIP-14		
Dim	Min	Max
A	3.710	4.310
A1	0.510	-
A2	3.200	3.600
B	0.380	0.570
B1	1.524 (BSC)	
c	0.204	0.360
D	18.800	19.200
E	6.200	6.600
E1	7.320	7.920
E2	8.400	9.000
e	2.540 (BSC)	
L	3.000	3.600
All Dimensions in mm		

Suggested Pad Layout

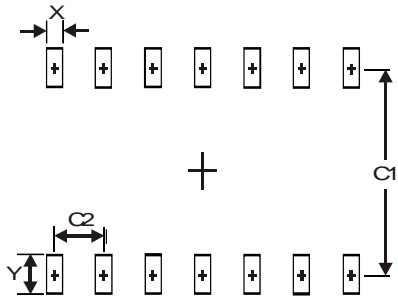
Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.

Package Type: SO-14



Dimensions	Value (in mm)
X	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65

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